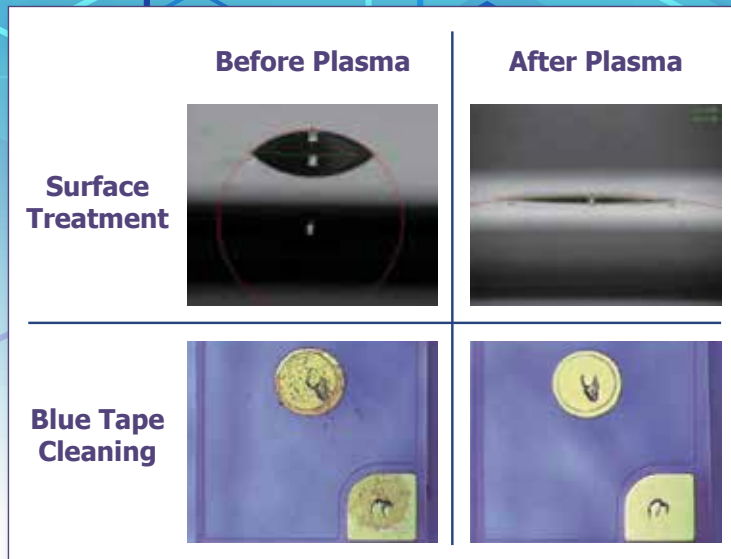


電漿清洗機

c sun

Plasma Treatment System

PRCS-BC06 / PRCM-BC10



專為微電子產品表面清潔與改質設計，
適用於各種金屬、玻璃、塑料的表面處理
Designed for surface cleaning and modification of
microelectronic products. Apply for a variety of metal,
glass and plastic surface treatment

機台特點 Characteristics

- 採用13.56MHz的RF電源搭配自動匹配輸出，達到最大功率輸出
Using 13.56MHz RF power supply with automatic matching output to achieve maximum power output.
- 利用活性自由基進行物理與化學反應，提高清潔效果
Chemical reaction and physical bombardment performed by free radicals and byproducts results in better effect of cleaning.
- 腔體內置可拆卸、調整的電極層架，以對應各種尺寸彈匣、Tray 盤和 Wafer
Equipped with removable and adjustable cassette to adapt to various sizes of magazines, trays and wafers.
- 操控採人性化圖形介面設計
User friendly touch screen interface.
- 佔地面積小
Small footprint.



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Leading in Thermal and UV Light Processing Equipment

PRCS-BC06 / PRCM-BC10 電漿清洗機

設備電力規格 Power	220V 3φ 50/60Hz 8kVA (PRCS-BC06) 220V 3φ 50/60Hz 12kVA (PRCM-BC10)
腔體材質 Material of chamber	Aluminum alloy
腔體內部尺寸 Interior chamber (mm)	W 495mm x D 450mm x H 500mm (PRCS-BC06) W 495mm x D 450mm x H 680mm (PRCM-BC10)
電漿源 Plasma source	CCP mode
承載盤數量 Number of tray	Max. 7 (PRCS-BC06) Max. 11 (PRCM-BC10)
射頻電源電力規格 Generator power	13.56MHz, 600W (PRCS-BC06) 13.56MHz, 1kW (PRCM-BC10)
製程氣體 Process gas	O ₂ 、Ar (Max. 3 gas lines)
氣體流量控制 Gas flow control	MFC (±1% of full scale)
泵浦規格 Standard pump	Dry pump, pumping speed >50cfm @60Hz
控制系統 Control system	PLC & touch panel
設備尺寸 Dimension	W 750mm x D 1200mm x H 2080mm (PRCS-BC06) W 750mm x D 1200mm x H 2180mm (PRCM-BC10)

Due to C SUN continuing efforts to improve their systems, these specifications are subject to change without notice.
受長期研發需要，本公司保有規格修改之權利，恕不另行通知

DM2023Q3-000-TW

應用 Applications

1. 焊線、模壓、黏晶、覆晶填膠等封裝製程前的表面改質
Surface modification before wire bonding, molding, mounting, flip chip filling and other packaging process.
2. 集成電路鍵合前表面清潔
Surface cleaning before IC bonding.
3. LED封裝前表面活化和清潔
Surface activation and cleaning before LED packaging.
4. 觸控模組膠合前的表面活化和清潔
Surface activation and cleaning before TP module lamination.
5. 攝像頭模組、指紋辨識模組表面清潔
Surface cleaning of CCD module and fingerprint identification module.
6. 其他電子材料表面活化和清潔
Surface activation and cleaning of other electronic materials.

